

REMARKS

The objection to the drawings has been corrected.

Claim 11 was rejected over Kinsman. However, Kinsman teaches a BT substrate. A BT substrate is a rigid substrate. It is essentially a fiberglass type substrate.

Claim 11 calls for a flexible package and there is no flexible package shown in the structure of Kinsman.

Claim 11 was also rejected based on Eslamy. However, all Eslamy teaches is an organic substrate. It is not indicated whether the substrate is a flex or a rigid substrate. Therefore, reconsideration of the rejection, based on Eslamy, is respectfully requested.

Claim 11 was also rejected over Manteghi. However, Manteghi does not teach a cavity in a flexible package. In Manteghi, there is no cavity. The die 10 is simply bonded on top of the base 12. In Figure 9, the die 40 is bonded atop the materials 42 and 46. There is no cavity for any die.

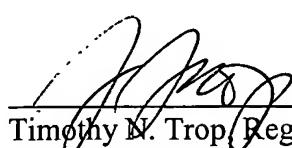
Therefore, reconsideration of the rejection of claims 11 and 12 is respectfully requested. On the same basis, reconsideration of the rejection of claims 16-19 is respectfully requested.

Likewise, reconsideration of claims 1-10 and 20-29, based on Eslamy, is respectfully requested.

With respect to claim 1, Eslamy does not teach a flexible substrate. With respect to claim 20, Eslamy does not teach a flexible substrate. Therefore, reconsideration of the rejection is respectfully requested.

Respectfully submitted,

Date: 3/6/05



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IN THE DRAWINGS

Figure 1 has been amended as indicated in red in the attached annotated marked-up drawing. A replacement sheet of Figure 1 is also attached.

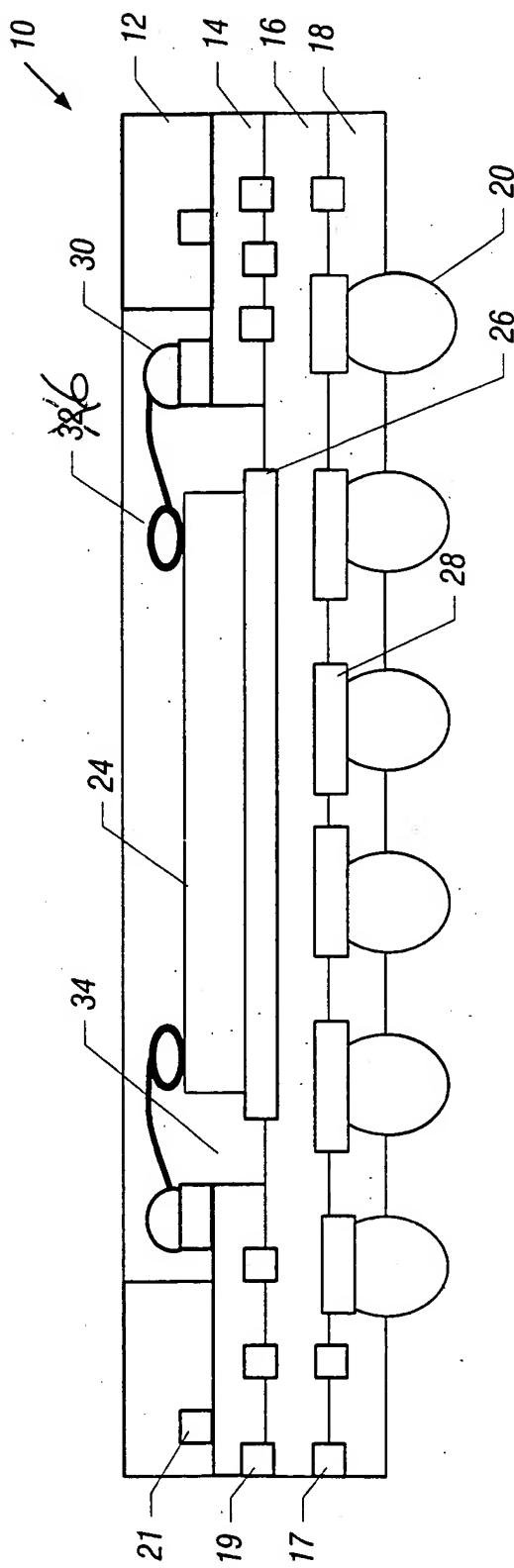


FIG. 1